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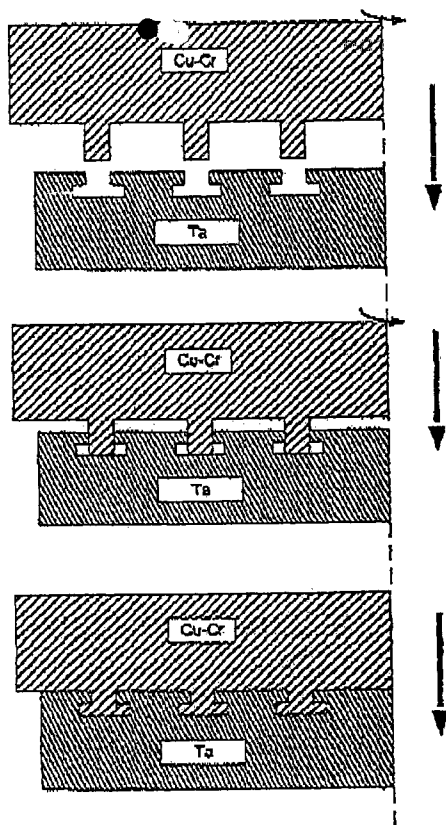
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(54) Title: METHOD OF FORMING A SPUTTERING TARGET ASSEMBLY AND ASSEMBLY MADE THEREFROM



Friction weld interlocking  
target assembly method.

(57) Abstract: A method of forming a sputtering target assembly and the sputtering target assembly made therefrom are described. The method includes bonding a sputtering target to a backing plate at a low temperature. Also described is a method of forming a sputtering target assembly such that a gap is formed between the sputtering target and the backing plate. Also described is a method of forming a sputtering target assembly providing a mechanism to prevent unintended sputtering into the backing plate.



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